

106TH CONGRESS
2D SESSION

S. 2165

To amend the Harmonized Tariff Schedule of the United States to provide for temporary duty-free treatment for certain semiconductor mold compounds.

IN THE SENATE OF THE UNITED STATES

MARCH 3, 2000

Mr. CRAIG (for himself and Mr. CRAPO) introduced the following bill; which was read twice and referred to the Committee on Finance

A BILL

To amend the Harmonized Tariff Schedule of the United States to provide for temporary duty-free treatment for certain semiconductor mold compounds.

1 *Be it enacted by the Senate and House of Representa-*
2 *tives of the United States of America in Congress assembled,*

3 **SECTION 1. TEMPORARY SUSPENSION OF DUTY ON CER-**
4 **TAIN SEMICONDUCTOR MOLD COMPOUNDS.**

5 (a) IN GENERAL.—Subchapter II of chapter 99 of
6 the Harmonized Tariff Schedule of the United States is
7 amended by inserting in numerical sequence the following
8 new heading:

“	9902.39.07	Thermosetting molding compounds of a kind suitable for use in the manufacture of semiconductor devices, via transfer molding process, containing 70 percent or more of silica, by weight, and having less than 75 parts per million of combined water extractable content of chloride, bromide, potassium and sodium (provided for in subheading 3907.30.00)	Free	No change	No change	On or before 12/31/2005	”.
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1 (b) EFFECTIVE DATE.—The amendment made by
 2 subsection (a) applies with respect to goods entered, or
 3 withdrawn from warehouse for consumption, on or after
 4 the 15th day after enactment of this Act.

